

## **AMENDMENTS TO THE CLAIMS:**

### **Complete Listing of Claims**

- 1    1. (currently amended)    An encapsulated chip assembly comprising:
  - 2                 a baseplate (12),
    - 3                 a chip (10) attached to the baseplate in such a way that its contact
    - 4                 surfaces (20) face away from the baseplate (12),
      - 5                 a layer (14) of a conductive material applied to the baseplate (12) and
      - 6                 arranged to around the chip (10), and having a support surface facing away from
      - 7                 the baseplate (12) which is at least as high as the surface of the chip (10) facing
      - 8                 away from the baseplate,
    - 9                 a cover plate (16) arranged on the layer of conductive material (14),
    - 10          whose one side, opposing the chip (10), being provided with one or more
    - 11          conductive surfaces (18), which are arranged in such a way that they form an
    - 12          electrical connection between the chip (10) and the layer of conductive material
    - 13          (14), the support surface of the layer (14) serving as a support for the cover plate
    - 14          (16).
  - 1    2. (original) The encapsulated chip according to claim 1, whereby the chip (10) is surrounded by a filler material that fills the open space between the baseplate (12) and the cover plate (16).
    - 1    3. (original) The encapsulated chip according to claim 2, further comprising an electrically conductive glue, which is to establish both the electrical and the mechanical connections between the contact surfaces (20) of the chip (10) and the conductive surface (18) or the conductive surfaces (18), respectively, of the cover plate (16).

1    4. (original) The encapsulated chip according to claim 2, further comprising an  
2    anisotropically conductive film (26) (ACF), which serves to establish both an  
3    electrical and a mechanical connection between the contact surfaces (20) of the  
4    chip (10) and the conductive surface (18) or the conductive surfaces (18),  
5    respectively, of the cover plate (16), and between the conductive surface (18) or  
6    the conductive surfaces (18), respectively, of the cover plate (16) and the  
7    conductive layer (14) applied to the baseplate (12).

1    5. (original) The encapsulated chip according to claim 4, whereby the filler  
2    material consists of the anisotropically conductive film (26).

1    6. (original) The encapsulated chip according to claim 1, where both the  
2    baseplate (12) and the cover plate (16) each consist of a flexible material.

1    7. (original) The encapsulated chip according to claim 1, where the height of the  
2    chip (10) is so low that it is rendered flexible.

1    8. (currently amended)   The encapsulated chip according to claim 7, where  
2    the chip (10) consists mainly of silicon and has a thickness of less than 50 µm  
3    ~~mm~~.

1    9. (original) The encapsulated chip according to claim 1, where the chip (10)  
2    comprises a transponder.

1    10. (original) The encapsulated chip according to claim 9, where the conductive  
2    layer (14) comprises an aerial.

1    11. (currently amended) An encapsulated chip assembly for a smart label  
2    comprising:

3         a flexible baseplate (12),

4         a chip (10) having a transponder attached to the baseplate in such a way  
5    that its contact surfaces (20) face away from the baseplate (12),

6         a layer (14) of a conductive material applied to the baseplate (12) and  
7    arranged to around the chip (10), and having a support surface facing away from  
8    the baseplate (12) which is at least as high as the surface of the chip (10) facing  
9    away from the baseplate, and forms an aerial for electrical signals for the  
10   transponder,

11         a cover plate (16) arranged on the layer of conductive material (14),  
12   whose one side, opposing the chip (10), being provided with one or more  
13   conductive surfaces (18), which are arranged in such a way that they form an  
14   electrical connection between the chip (10) and the layer of conductive material  
15   (14), the support surface of the layer (14) serving as a support for the cover plate  
16   (16).

1    12. (original) The encapsulated chip according to claim 11, further comprising an  
2    electrically conductive glue, which is to establish both the electrical and the  
3    mechanical connections between the contact surfaces (20) of the chip (10) and  
4    the conductive surface (18) or the conductive surfaces (18), respectively, of the  
5    cover plate (16).

1    13. (original) The encapsulated chip according to claim 12, further comprising an  
2    anisotropically conductive film (26) (ACF), which serves to establish both an  
3    electrical and a mechanical connection between the contact surfaces (20) of the  
4    chip (10) and the conductive surface (18) or the conductive surfaces (18),  
5    respectively, of the cover plate (16), and between the conductive surface (18) or  
6    the conductive surfaces (18), respectively, of the cover plate (16) and the  
7    conductive layer (14) applied to the baseplate (12).

1    14. (original) The encapsulated chip according to claim 11, where the height of  
2    the chip (10) is so low that it is rendered flexible.

1    15. (original) The encapsulated chip according to claim 14, where the chip (10)  
2    consists mainly of silicon and has a thickness of less than 50 µm.

Claims 16-20                 (canceled)